| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|---|----------------------------------|---------------------|---------|------------------|
| L1 | 4163 | 257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls. 257/769.ccls. 257/774.ccls. | US-PGPUB; USPAT | OR | OFF | 2005/03/02 16:31 |
| L2 | 0 | (257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls. 257/768.ccls. 257/769.ccls. 257/774.ccls.) and ((gate with (platinum pt rhodium rh ruthenium ru iridium ir osmium os)) same ((plug interconnect wiring trace via contact) with (copper cu)) same (source drain)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 16:32 |
| L3 | 17 | (257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls. 257/768.ccls. 257/769.ccls. 257/774.ccls.) and (polysilicon with gate with (platinum pt rhodium rh ruthenium ru iridium ir osmium os)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 16:32 |
| L4 | 21 | ((gate with (platinum pt rhodium rh ruthenium ru iridium ir osmium os)) same ((plug interconnect wiring trace via contact) with (copper cu)) same (source drain)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 16:57 |
| L5 | 40 | (257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls. 257/768.ccls. 257/769.ccls. 257/774.ccls.) and (gate same ((plug interconnect wiring trace via contact) with (copper cu)) same (source drain)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 17:15 |
| L6 | 18 | (gate with ((plug contact) near2 (copper cu)) with (source drain)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 17:26 |
| L7 | 33 | 438/620.ccls. and ((plug contact) with (copper cu)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 17:28 |
| L8 | 1 | ((insulat\$4 dielectric oxide dioxide nitride interlayer) with (silicon si)) and ((unit adj cell) (lattice near4 (constant mismatch\$4 match\$4))) and ((atom\$2 near (radius radii)) (bond\$4 near energy)) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/02 17:32 |
| L9 | 35 | ((atom\$2 near (radius radii)) (bond\$4 near energy)) and (semiconductor silicon si wafer substrate) and (copper cu) and (rhodium rh ruthenium ru iridium ir osmium os platinum pt) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/02 17:33 |

| L10 | 8 | (semiconductor silicon si wafer substrate) and ((interconnect\$5 metal\$1is\$7 metal\$1iz\$7) same ((platinum pt) near4 (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer")) same ((osmium os) with (palladium pd cobalt co nickel ni titanium ti) with (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer"))) | US-PGPUB; USPAT | OR | ON | 2005/03/02 17:35 |
|-----|-----|--|----------------------------------|----|----|------------------|
| L11 | 300 | ((atom\$2 near (radius radii)) (bond\$4 near energy)) and (semiconductor silicon si wafer substrate) and ((copper cu) same (rhodium rh ruthenium ru iridium ir osmium os platinum pt) same (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer")) | US-PGPUB; USPAT | OR | ON | 2005/03/02 17:39 |
| L12 | 148 | ((insulat\$4 dielectric oxide dioxide nitride interlayer) with (silicon si)) and ((unit adj cell) (lattice near4 (constant mismatch\$4 match\$4)) (atom\$2 near (radius radii)) (bond\$4 near energy)) and ((film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer") with (conduct\$5 platinum pt copper cu silver ag gold au rhodium rh ruthenium ru iridium ir osmium os palladium pd cobalt co nickel ni titanium ti)) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/02 18:04 |
| L13 | 640 | (257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls. 257/768.ccls. 257/769.ccls. 257/774.ccls.) and ((copper cu silver ag gold au platinum pt) same ((rhodium rh ruthenium ru iridium ir osmium os platinum pt) with (palladium pd cobalt co nickel ni titanium ti))) | US-PGPUB; USPAT | OR | ON | 2005/03/02 18:07 |
| L14 | 260 | (semiconductor silicon si wafer substrate) and ((insulat\$4 dielectric oxide dioxide nitride interlayer) with (silicon si)) and ((unit adj cell) (lattice near4 (constant mismatch\$4 match\$4))) and ((atom\$2 near (radius radii)) (bond\$4 near energy)) | US-PGPUB; USPAT | OR | ON | 2005/03/02 18:07 |

| L15 | 426 | (semiconductor silicon si wafer substrate) and ((interconnect\$5 metal\$1is\$7 metal\$1iz\$7) same ((copper cu silver ag gold au) near4 (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer")) same ((rhodium rh ruthenium ru iridium ir osmium os platinum pt) with (palladium pd cobalt co nickel ni titanium ti) with (film layer multilayer bilayer trilayer" | US-PGPUB; USPAT | OR | ON | 2005/03/02 18:18 |
|-----|-----|---|--------------------|----|----|------------------|
| | | trilayer "bi-layer" "tri-layer" "multi-layer") with (element constituent consist\$3 compris\$3 atom metal))) | , | | | |